

ABSTRACT OF THE DISCLOSURE

Methods and apparatus for removing minute particle(s) from a substrate. The methods include arranging an energy transfer medium having a predetermined thickness under and around one or more particle(s) to be removed, and irradiating the energy transfer medium and/or the surface of the substrate with pulsed energy, wherein the predetermined thickness of the energy transfer medium is selected so that viscous and other drag forces within the energy transfer medium are sufficient to cause the one or more particle(s) to be removed from the surface of the substrate. The apparatus include a tailored energy transfer medium application unit configured to control application of an energy transfer medium onto the surface of a substrate, and a tailored energy source that irradiates the energy transfer medium and/or the substrate with a tailored energy pulse or pulses, wherein the energy transfer medium application unit controls application of the energy transfer medium in accordance with a dimension of at least one of the particle(s).